

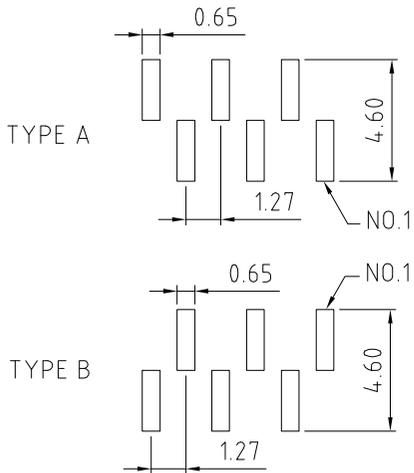
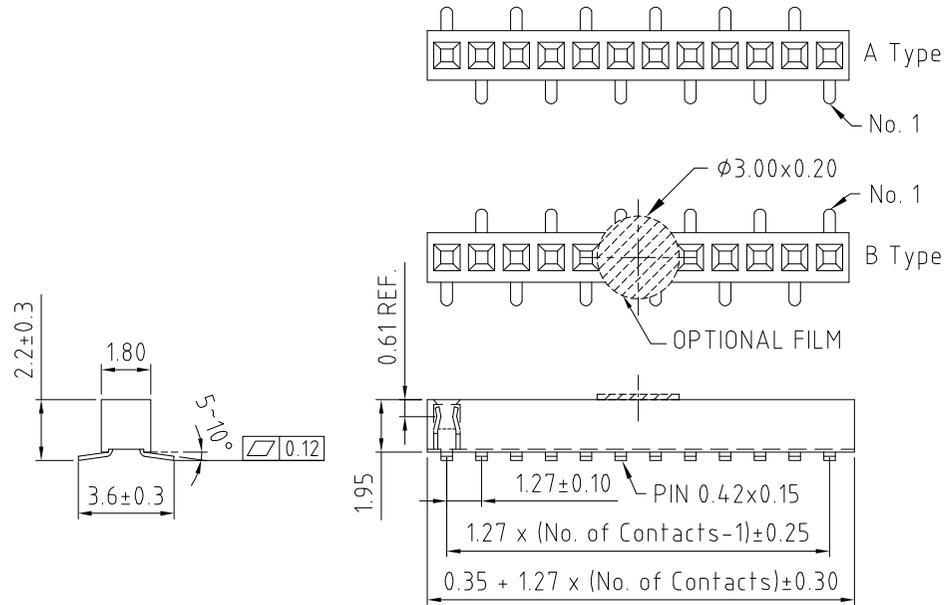
BB02-CY :- 1.27mm ( 0.05" ) STRAIGHT SMD FEMALE HEADER, SINGLE ROW - 2 TO 40 CONTACTS, DUAL ENTRY

SPECIFICATIONS

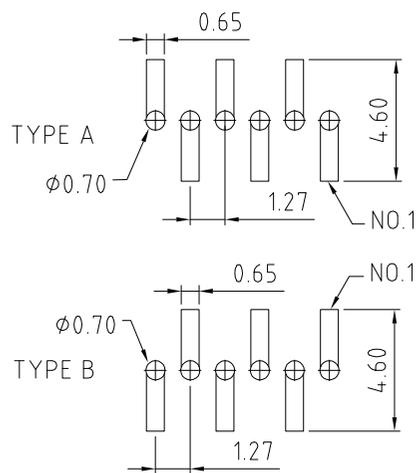
|                         |                                  |
|-------------------------|----------------------------------|
| CURRENT RATING          | 1 AMP                            |
| INSULATOR RESISTANCE    | 1000 MEGOHMS MIN.                |
| DIELECTRIC WITHSTANDING | 300 V AC/DC                      |
| CONTACT RESISTANCE      | 20m OHMS MAX.                    |
| OPERATING TEMPERATURE   | -40°C TO +105°C                  |
| CONTACT MATERIAL        | PHOSPHOR BRONZE                  |
| INSULATOR MATERIAL      | THERMOPLASTIC, UL 94V-0          |
|                         | STANDARD: LCP + 30% G/F          |
| PLATING                 | GOLD OR TIN OVER 30~50U" NICKEL  |
| SOLDERABILITY           | IR REFLOW: 280°C FOR 10 SEC      |
|                         | MANUAL SOLDER: 380°C FOR 3-5 SEC |

- NOTES:
1. RECOMMENDED MATING PIN LENGTH FOR TOP ENTRY: 1.5MM.  $\triangle$   $\triangle$
  2. PARTS WITH SMALL NUMBER OF CONTACTS MAY BE PACKED IN BOX INSTEAD OF TUBE.

MATES WITH: - (0.40MM SQUARE PINS)  
 BB02-NA BB02-NC BB02-5B  
 BB02-NB BB02-NS



RECOMMENDED PCB LAYOUT FOR TOP ENTRY (TOLERANCE:  $\pm 0.05$ )



RECOMMENDED PCB LAYOUT FOR BOTTOM ENTRY (TOLERANCE:  $\pm 0.05$ )

HOW TO ORDER



NO. OF CONTACTS:  
02 TO 40

FOOTPRINT TYPE:  
A = A TYPE  
B = B TYPE

PACKAGING OPTIONS:  
3 = TUBE  
4 = TUBE & FILM (MIN. 4 PINS)  
6 = TAPE & REEL  
7 = TAPE & REEL & FILM (MIN. 4 PINS)  
(See Note 2.)

CONTACT PLATING OPTIONS:  $\triangle$   
 K = GOLD FLASH (STANDARD)  
 A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL  
 B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL  
 C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL  
 T = BRIGHT TIN  
 M = MATT TIN

|      |  |
|------|--|
| REV. | DATE & DSN   |
| 10   | 20/07/06 - NYW RELEASE   |
| 11   | 24/07/06 - NYW DRAWING MODIFICATION                              |
| 12   | 09/05/07 - NYW ADD NOTES 1                                       |
| 13   | 16/07/07 - CHC REMOVE SELECTIVE GOLD CONTACT PLATING             |
| 14   | 05/05/08 - CHC DISCONTINUATION OF MATE WITHL. AHEAD MATINT PART. |
| 15   | 30/07/08 - CHC DRAWING MODIFICATION. AHEAD MATINT PART.          |
| 16   | 20/08/09 - CHC AHEAD NOTES 1                                     |
| 17   | 25/08/11 - NYW AHEAD FILM DRAWING.                               |
| 18   | 02/09/11 - NYW AHEAD INSULATOR MATERIAL                          |
| 19   | 26/02/13 - NYW ADD NOTE 2  |
| 20   | 17/02/16 - NYW ADD NOTES TO FILM PACKAGING OPTIONS.              |

|        |             |             |   |          |              |
|--------|-------------|-------------|---|----------|--------------|
| Scale: | 5:1         | THIRD ANGLE | Unstated Tolerances:<br>X $\pm 0.30$<br>X $\pm 0.25$<br>XX $\pm 0.15$<br>XXX $\pm 0.10$ | Material | SEE NOTE     |
| Drawn: | CHC         |             |   |          |              |
| App'd: | XXXX        | Title       | SOCKET  |          | NOT TO SCALE |
| Date:  | 17 FEB. '16 | Revision:   | 2.0   | UNIT:    | mm           |

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|                 |            |
|-----------------|------------|
| Type:           | BB02-CY    |
| Drawing Number: | BB02-CY    |
| Sheet           | 1 of 1     |
| Drawing         | © E and OE |